

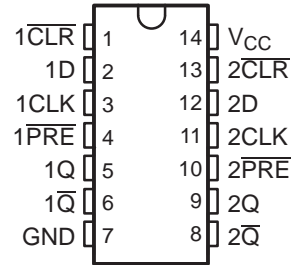
## FEATURES

- **Controlled Baseline**
  - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –40°C to 125°C and –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree <sup>(1)</sup>**
- **Operates From 2 V to 3.6 V**

(1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- **Inputs Accept Voltages to 5.5 V**
- **Max  $t_{pd}$  of 5.2 ns at 3.3 V**
- **Typical  $V_{OLP}$  (Output Ground Bounce) <0.8 V at  $V_{CC} = 3.3 V, T_A = 25^\circ C$**
- **Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot) >2 V at  $V_{CC} = 3.3 V, T_A = 25^\circ C$**

D OR PW PACKAGE  
(TOP VIEW)



## DESCRIPTION/ORDERING INFORMATION

The SN74LVC74A dual positive-edge-triggered D-type flip-flop is designed for 2.7-V to 3.6-V  $V_{CC}$  operation.

A low level at the preset ( $\overline{PRE}$ ) or clear ( $\overline{CLR}$ ) inputs sets or resets the outputs, regardless of the levels of the other inputs. When  $\overline{PRE}$  and  $\overline{CLR}$  are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device as a translator in a mixed 3.3 V/5 V system environment.

### ORDERING INFORMATION<sup>(1)</sup>

$T_A$	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	SOIC – D	Reel of 2500	SN74LVC74AQDREP	LVC74AE
	TSSOP – PW	Reel of 2000	SN74LVC74AQPWREP	LVC74AE
–55°C to 125°C	SOIC – D	Reel of 2500	SN74LVC74AMDREP	LVC74AM
	TSSOP – PW	Reel of 2000	SN74LVC74AMPWREP	LVC74AM

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).  
 (2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

# SN74LVC74A-EP

## DUAL POSITIVE EDGE TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

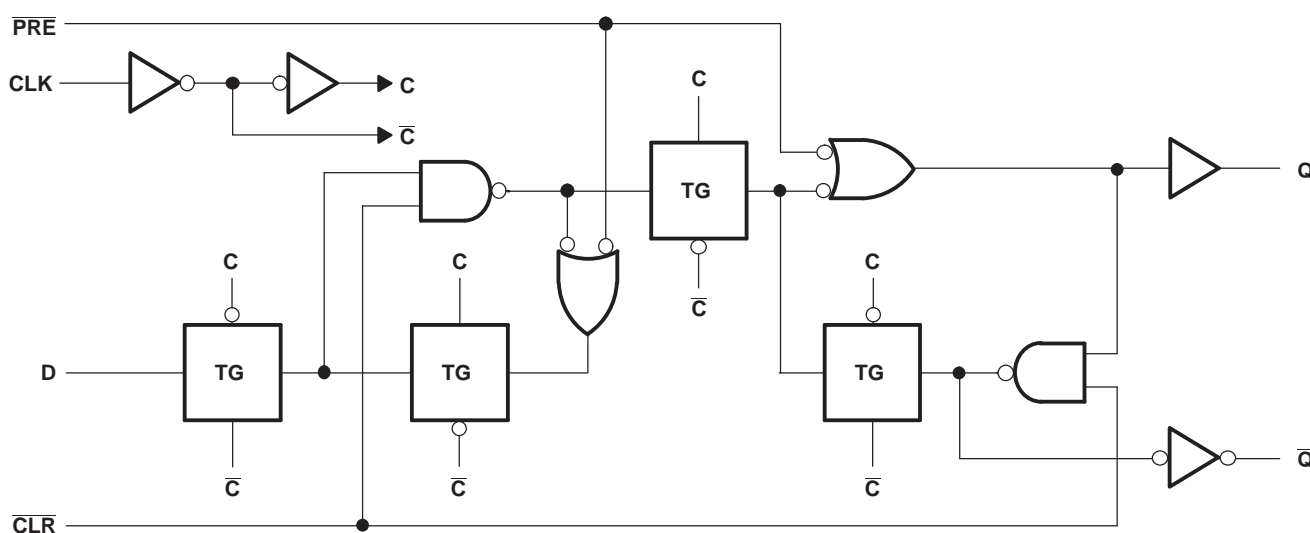
SCAS751C—DECEMBER 2003—REVISED SEPTEMBER 2007

FUNCTION TABLE

INPUTS				OUTPUTS	
PRE	$\overline{\text{CLR}}$	CLK	D	Q	$\overline{\text{Q}}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H <sup>(1)</sup>	H <sup>(1)</sup>
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q <sub>0</sub>	$\overline{\text{Q}}_0$

(1) This configuration is nonstable; that is, it does not persist when  $\overline{\text{PRE}}$  or  $\overline{\text{CLR}}$  returns to its inactive (high) level.

LOGIC DIAGRAM, EACH FLIP-FLOP (POSITIVE LOGIC)



### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	-0.5	6.5	V
V <sub>I</sub>	Input voltage range <sup>(2)</sup>	-0.5	6.5	V
V <sub>O</sub>	Output voltage range <sup>(2)(3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50 mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50 mA
I <sub>O</sub>	Continuous output current			±50 mA
	Continuous current through V <sub>CC</sub> or GND			±100 mA
θ <sub>JA</sub>	Package thermal impedance <sup>(4)</sup>	D package		86 °C/W
		PW package		113
T <sub>stg</sub>	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V<sub>CC</sub> is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

### Recommended Operating Conditions<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	Operating		2 3.6 V
		Data retention only		1.5
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V		2 V
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V		0.8 V
V <sub>I</sub>	Input voltage	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2.7 V		-12 mA
		V <sub>CC</sub> = 3 V		-24
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7 V		12 mA
		V <sub>CC</sub> = 3 V		24
Δt/Δv	Input transition rise or fall rate			10 ns/V
T <sub>A</sub>	Operating free-air temperature	M suffix		-55 125 °C
		Q suffix		-40 125

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. See the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN74LVC74A-EP

## DUAL POSITIVE EDGE TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

SCAS751C–DECEMBER 2003–REVISED SEPTEMBER 2007

### Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	2.7 V to 3.6 V	V <sub>CC</sub> - 0.2			V
	I <sub>OH</sub> = -12 mA	2.7 V	2.2			
		3 V	2.4			
	I <sub>OH</sub> = -24 mA	3 V	2.2			
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	2.7 V to 3.6 V			0.2	V
	I <sub>OL</sub> = 12 mA	2.7 V			0.4	
	I <sub>OL</sub> = 24 mA	3 V			0.55	
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	3.6 V			±5	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V			10	μA
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V			500	μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		5		pF

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

### Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency	83		100		MHz
t <sub>w</sub>	Pulse duration	PRE or CLR low		3.3		ns
		CLK high or low		3.3		
t <sub>su</sub>	Setup time before CLK↑	Data		3		ns
		PRE or CLR inactive		2		
t <sub>h</sub>	Hold time, data after CLK↑	1		1		ns

### Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

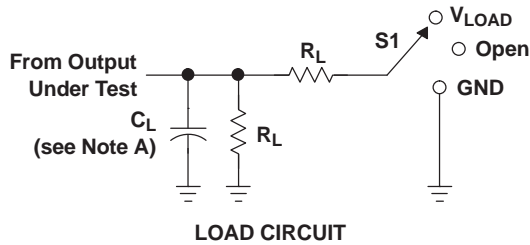
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
f <sub>max</sub>			83		100		MHz
t <sub>pd</sub>	CLK	Q or Q̄	6		1	5.2	ns
	PRE or CLR		6.4		1	5.4	

### Operating Characteristics

T<sub>A</sub> = 25°C

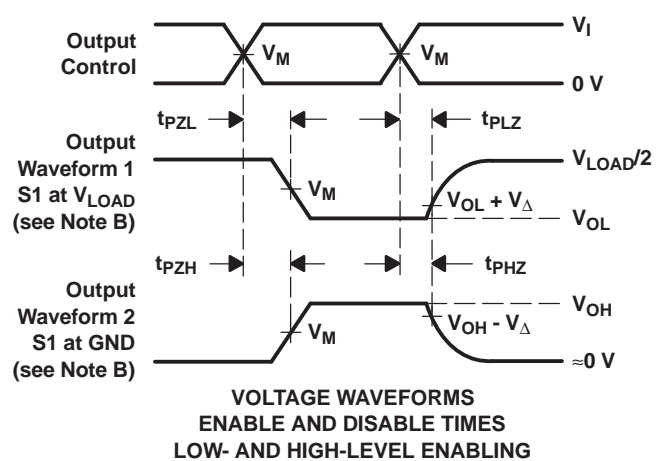
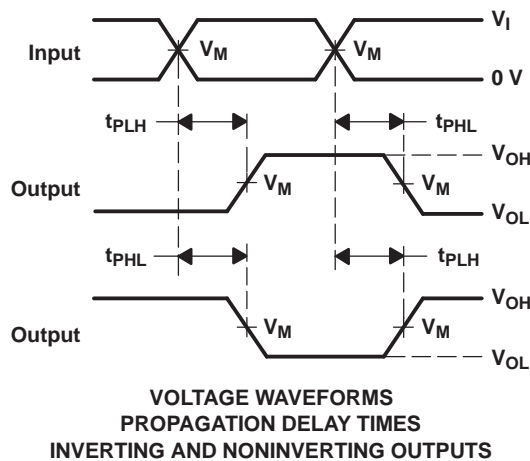
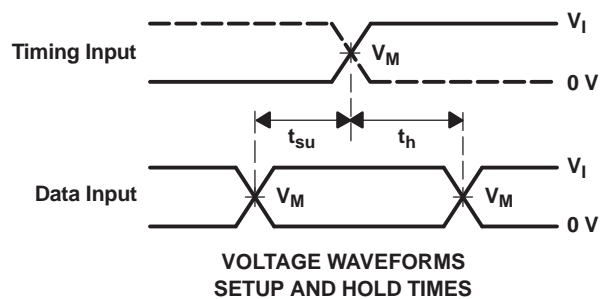
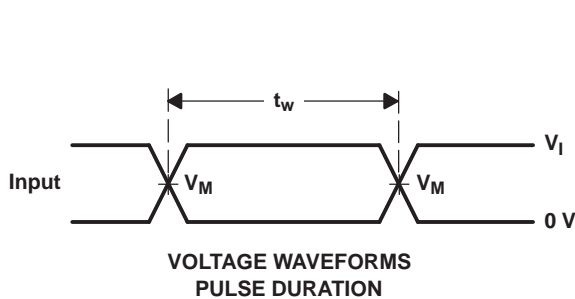
PARAMETER	TEST CONDITIONS	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT
		TYP	TYP	
C <sub>pd</sub>	f = 10 MHz	47	51	pF

PARAMETER MEASUREMENT INFORMATION



TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
2.7 V	2.7 V	$\leq 2.5$ ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	$\leq 2.5$ ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ .
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LVC74AMDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74AMPWREP	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74AQDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC74AQPWREP	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04669-01XE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04669-01YE	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04669-02XE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04669-02YE	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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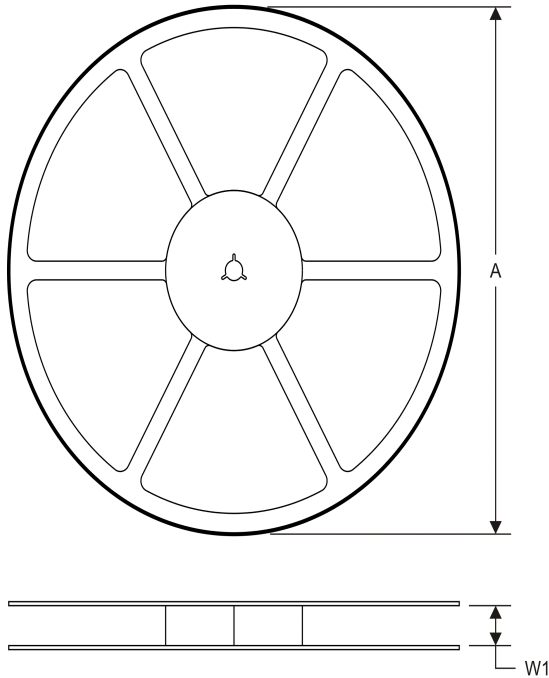
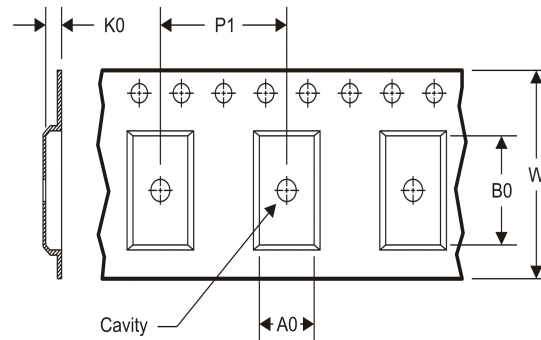
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**OTHER QUALIFIED VERSIONS OF SN74LVC74A-EP :**

- Catalog: [SN74LVC74A](#)
- Automotive: [SN74LVC74A-Q1](#)
- Military: [SN54LVC74A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC74AMDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC74AMPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC74AQDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC74AQPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC74AMDREP	SOIC	D	14	2500	333.2	345.9	28.6
SN74LVC74AMPWREP	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74LVC74AQDREP	SOIC	D	14	2500	333.2	345.9	28.6
SN74LVC74AQPWREP	TSSOP	PW	14	2000	367.0	367.0	35.0

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

# MECHANICAL DATA

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

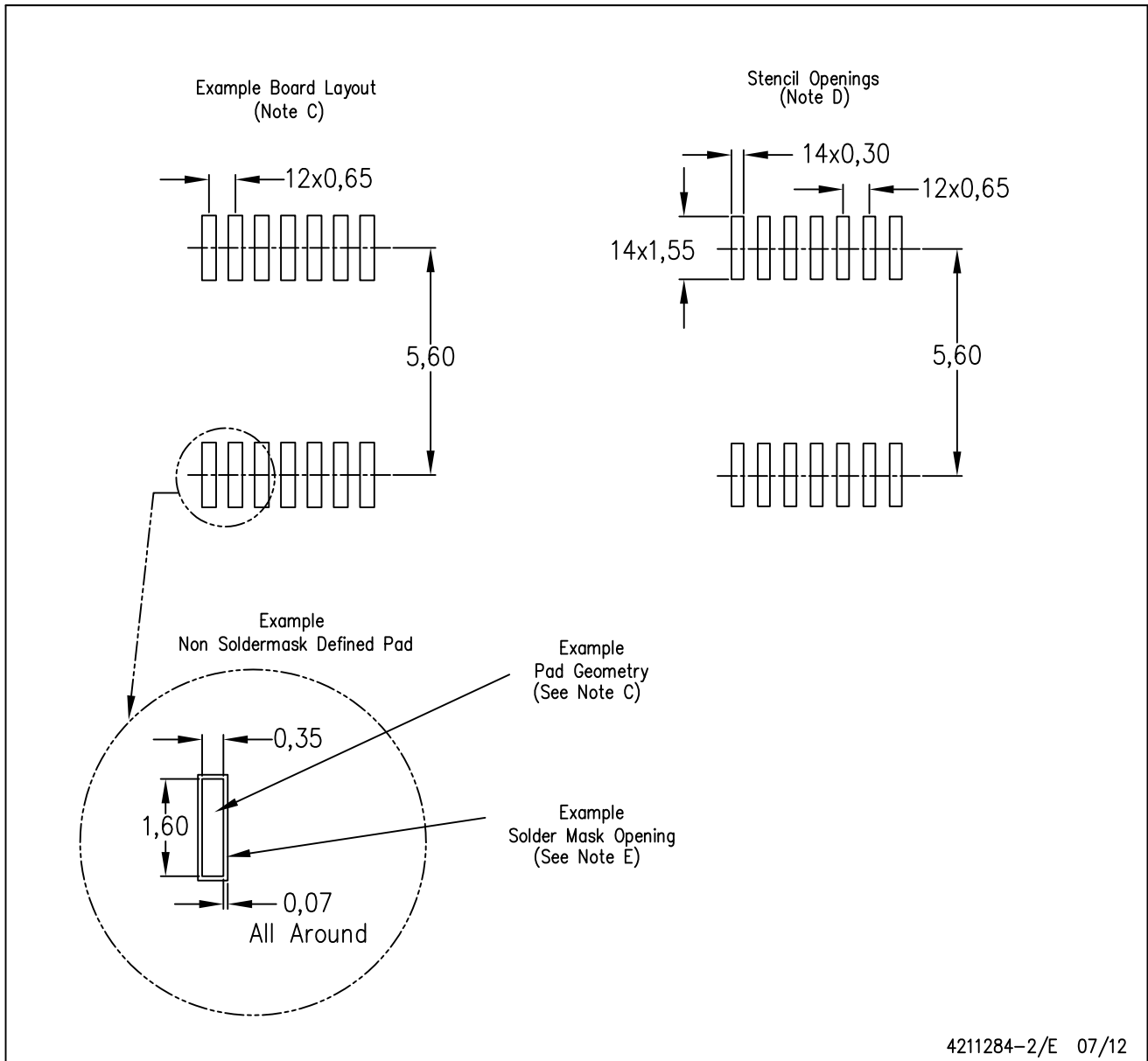


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- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

### Products

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### Applications

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## Стандарт Электрон Связь

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию .

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России , а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научно-исследовательскими институтами России.

С нами вы становитесь еще успешнее!

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